

#### NOT RECOMMENDED FOR NEW DESIGN **USE DMP2045U**



**DMP2100U** 

#### P-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

BV <sub>DSS</sub>	Rds(on) max	Package	I <sub>D</sub> T <sub>A</sub> = +25°C
-20V	38mΩ @ V <sub>GS</sub> = -10V		-4.3A
	43mΩ @ V <sub>GS</sub> = -4.5V	SOT23	-4.0A
	75mΩ @ V <sub>GS</sub> = -2.5V		-2.8A

## **Description**

This new generation MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance. making it ideal for high efficiency power management applications.

### **Applications**

- Load Switch
- **Power Management Functions**

#### **Features**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **ESD Protected Up To 3kV**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotive-

This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

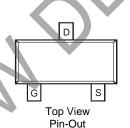
https://www.diodes.com/quality/product-definitions/

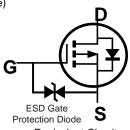
### **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
  - Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Terminals Connections: See Diagram Below
- Weight: 0.008 grams (Approximate)









**Equivalent Circuit** (Note 4)

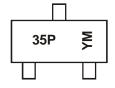
### Ordering Information (Note 5)

Part Num	per	Compliance	Case	Packaging			
DMP2100U-7 Standard		SOT23	3,000/Tape & Reel				
Notes: 1 No purpo	1. No purposely added lead, Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.						

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. The ESD gate protection diode is only designed to protect against ESD events. No gate-source voltage greater than the maximum VGSS rating (given on page 2) can be applied.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# Marking Information



35P = Product Type Marking Code YM = Date Code Marking Y = Year (ex: G = 2019)M = Month (ex: 9 = September)

Date Code Key

Year	2008	~	2017	2018	201	9 20	)20 2	2021	2022	2023	2024	2025
Code	V	~	Е	F	G	i	Н	I	J	K	L	М
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



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# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage		VDSS	-20	V	
Gate-Source Voltage (Note 6)	Vgss	±10	V		
Continuous Drain Current (Note 9) Vac. 40V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	lo	-4.3 -3.4	Α
Continuous Drain Current (Note 8) Vgs = -10V	t<5s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-5.5 -4.3	Α
Maximum Continuous Body Diodes Forward Curre	nt (Note 8)	Is	-2	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 19	6)	I <sub>DM</sub>	-30	Α	
Pulsed Body Diodes Forward Current (10µs Pulse,	Ism	-30	А		

# Thermal Characteristics

				7	
Characteristic		Syn	nbol	Value	Unit
Total Power Dissipation (Note 7)	$T_A = +25$ °C		25	0.8	W
Total Fower Dissipation (Note 1)	$T_A = +70$ °C	- P <sub>D</sub>		0.5	٧٧
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	RеJA		161	°C/W
Thermal Resistance, Junction to Ambient (Note 1)	t<5s			96	
Total Power Dissipation (Note 8)	T <sub>A</sub> = +25°C	Pn		1.3	w
Total Fower Dissipation (Note 8)	$T_A = +70^{\circ}C$		D	0.8	v v
Thermal Resistance, Junction to Ambient (Note 8)	Steady State	Reja		99	
Thermal Resistance, Junction to Ambient (Note 6)	t<5s	K	ÐЈА	60	°C/W
Thermal Resistance, Junction to Case (Note 8)		R	9JC	15	
Operating and Storage Temperature Range		T <sub>J</sub> ,	Тѕтс	-55 to +150	°C

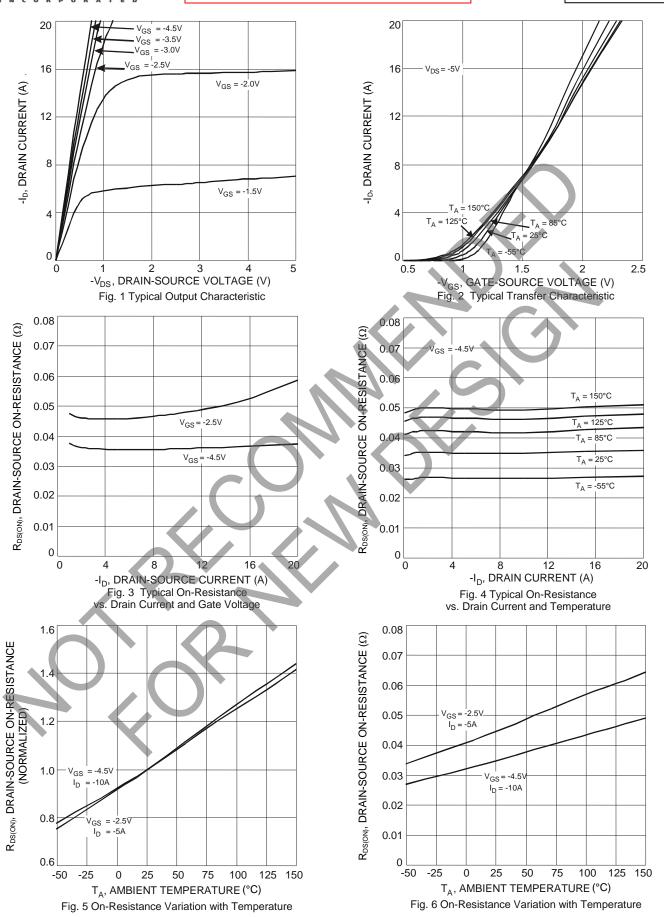
# Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BVDSS	-20	+	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$
Zero Gate Voltage Drain Current	loss	~ \	7	-1	μΑ	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V
Gate-Source Leakage	Igss	/ -		±10	μΑ	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	Vgs(TH)	-0.3	_	-1.4	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$
			25	38		$V_{GS} = -10V, I_D = -3.5A$
Static Drain-Source On-Resistance			29	43	mΩ	$V_{GS} = -4.5V, I_{D} = -3A$
Static Drain-Source Off-Resistance	RDS(ON)	_	37	75	11122	V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -1A
			47	_		Vgs = -1.8V, ID = -0.5A
Forward Transfer Admittance	Y <sub>fs</sub>	_	3	_	S	V <sub>DS</sub> = -5V, I <sub>D</sub> = -4A
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	Ciss	1	216	_	pF	15)/ )/ 0)/
Output Capacitance	Coss	_	90	_	pF	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	24	_	pF	1 = 1.0W112
Gate Resistance	Rg	_	250	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1.0MHz$
SWITCHING CHARACTERISTICS (Note 10)						
Total Gate Charge	Qg	_	9.1	_	nC	15)/ )/ 10)/
Gate-Source Charge	Qgs	_	1.6	_	nC	Vgs = -4.5V, Vps = -10V
Gate-Drain Charge	Qgd	_	2.0	_	nC	ID = -4A
Turn-On Delay Time	t <sub>D(ON)</sub>		80		ns	
Turn-On Rise Time	t <sub>R</sub>	_	155		ns	V <sub>DS</sub> = -10V, V <sub>GS</sub> = -4.5V,
Turn-Off Delay Time	tD(OFF)	_	688	_	ns	$R_D = 2.5\Omega$ , $R_G = 3.0\Omega$
Turn-Off Fall Time	t <sub>F</sub>	_	423		ns	

Notes:

- 6. AEC-Q101  $V_{GS}$  maximum is  $\pm 9.6 V$ .
- 7. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

  8. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.





# NOT RECOMMENDED FOR NEW DESIGN USE DMP2045U

### **DMP2100U**

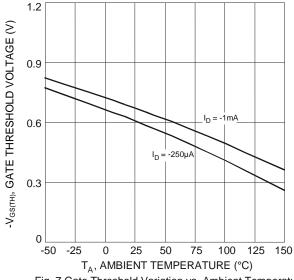
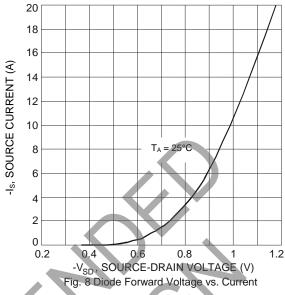
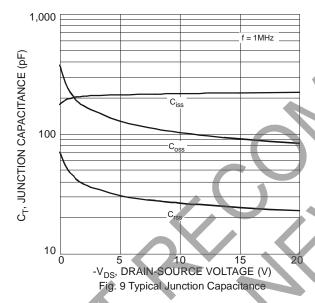
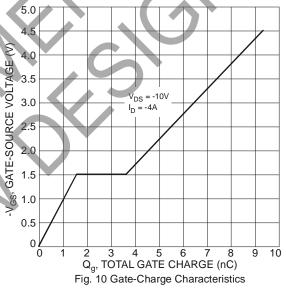


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







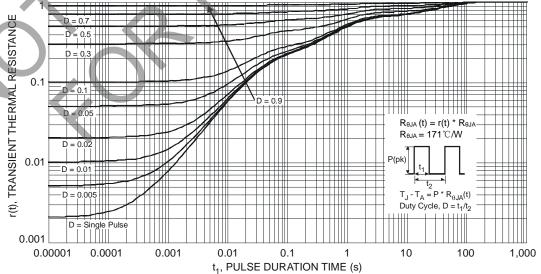


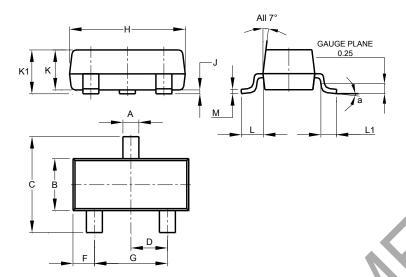
Fig. 11 Transient Thermal Response



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT23

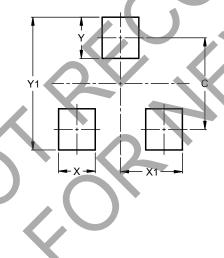


SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
H	2.80	3.00	2.90				
7	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
M	0.085	0.150	0.110				
a	0°	8°					
All Dimensions in mm							

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SOT23



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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